

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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CL HROSE ELE	I)TEMPERATURE RISE INCLUDED WHEN ENERGIZE 2)THIS STORAGE INDICATES A LONG-TERM STORAGE FOR THE UNUSED PRODUCT BEFORE THE BOARD Unless otherwise specified, refer to MIL- Note QT:Qualification Test AT:Assurance Test	OCLUERABILITY	RESISTANCE TO SOLDERING HEAT	CORROSION SALT MIST HYDROGEN SULPHIDE	NTAL	VIBRATION	MECHANICAL CHARACTERISTICS MECHANICAL 100 TIMES INSE OPERATION	RESISTANCE VOLTAGE PROOF	CONTACT RESISTANCE 100 mA	MARKING CHADAC	CONSTRUCTION CENERAL EXAMINATION			OPERATING TEMPERATURE RANGE	APPLICABLE STANDARD	> D	_
ELECTRIC CO., LTD. SPECIFICATION DRAWING NO. ELC4 – 082601-21	WHEN ENERGIZED. IG-TERM STORAGE STATE ORE THE BOARD MOUNTED. refer to MIL-STD-1344. Assurance Test ×:Applicable Test	SOLDERED AT SOLDER TEMPERATURE, 245 ± 3 °C FOR IMMERSION DURATION, 3 s.(MIL -STD-202)	(TEST STANDARD: JEIDA-39) 1) REFLOW SOLDERING :250 °C MAX, 220 °C MIN, FOR 60 s 2) SOLDERING IRON 360 °C, FOR 5 s	TIME 30 → 5 MAX → 30 → 5 MAX min UNDER 5 CYCLES. EXPOSED IN 5 % SALT WATER SPRAY FOR 48 h. EXPOSED IN 10 PPM FOR 96 h.	ACTERISTICS OSED AT 40±2°C, 90 ~ 95%, 96 PERATURE-55→+15~+35→+85→+15~+38	FREQUENCY 10 TO 55 Hz, AMPLITUDE: 1.5 mm, AT 2 h FOR 3 DIRECTION. 490 m/s ² , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS	ACTERISTICS 100 TIMES INSERTIONS AND EXTRACTIONS.	500 V DC. 650 V AC FOR 1 min.	100 mA (DC OR 1000 Hz).	CONFIRMED VISUALLY.	CONSTRUCTION VISIBILY AND BY MEASURING INSTRUMENT	SPECIFICATIONS	2 A	PANGE -55 °C TO 85 °C ⁽¹⁾		> \	
SHEET PART NO. A3A. CODE NO. CL 6	DRAWN DESIGNED CHECKED T.NODA H. JOH H. Designed O5.03.31 (05.03.31) (05.03.31)	A NEW UNIFORM COATING OF SÖLDER SHALL COVER A MINIMUM OF 95% OF T SURFACE BEING IMMERSED.	NO DEFORMATION OF CAS EXCESSIVE LOOSENESS OF TERMINALS.	DR ①CONTACT RESISTANCE: ②NO HEAVY CORROSION	①CONTACT RE ②INSULATION I	①NO ELECTRICAL DISCONTINUITY OF 1 µs. ②NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	①CONTACT RE ②NO DAMAGE, OF PARTS.	1000 MΩ MIN. NO FLASHOVER OR BREAKDOWN.	15 mΩ MAX.		ACCORDING TO DRAWING		STORAGE HUMIDITY RANGE	TEMPERATURE RANGE OPERATING HUMIDITY RANGE			
1-**PA-2SV(71)	Mower H. Glawar.	TING OF SÖLDER X NUM OF 95% OF THE RSED.		20 mΩ MAX.	SISTANCE: 20 mΩ MAX. XRESISTANCE: 1000 MΩ MIN. CRACK AND LOOSENESS X	K AND LOOSENESS X	SISTANCE: 20 mΩ MAX. X	REAKDOWN. ×	×	× >	2	NTO	40 % TO 70 % ⁽²⁾	-10 °C TO 60 °C ⁽²⁾			_

